Abstracts

Coplanar Waveguide Based, Dielectric Coated Flip Chip Monolithic Microwave Integrated Circuit, a Paradigm Shift in MMIC Technology

C.P. Wen, W.D. Wong, C.K. Pao, J.L. Snopkowski and D.L. Ingram. "Coplanar Waveguide Based, Dielectric Coated Flip Chip Monolithic Microwave Integrated Circuit, a Paradigm Shift in MMIC Technology." 1995 Microwave and Millimeter-Wave Monolithic Circuits Symposium Digest 95.1 (1995 [MCS]): 123-126.

The status of a coplanar waveguide based, novel dielectric coated, mechanically rugged, flip-chip, monolithic microwave integrated circuit (MMIC) technology will be described. This technology is ideal for low-cost, multi-chip transmit/receive (T/R) module applications. Equivalent circuit and thermal models, and the fabrication procedure of flip-chip MMICs featuring T-shaped plated silver thermal bumps will be presented along with test results obtained on components designed using these circuit element models. * The work is partially supported by a cooperative grant from the Advanced Technology Program (ATP) Office of the National Institute of Standards and Technology (NIST).

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